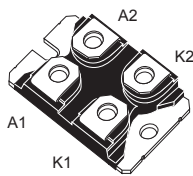
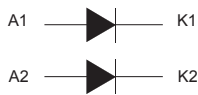



## Automotive 170 V, 2 x 100 A, high voltage power Schottky rectifier


**ISOTOP**

### Features

- AEC-Q101 qualified 
- PPAP capable
- Operating  $T_j$  from  $-40\text{ °C}$  to  $+175\text{ °C}$
- Negligible switching losses
- Low leakage current
- Avalanche rated
- Good trade-off between leakage current and forward voltage drop
- Insulated package ISOTOP comply with UL1557 insulation:
  - Insulated voltage:  $2500\text{ V}_{\text{RMS}}$  sine
- ECOPACK2 compliant component

### Applications

- DC/DC converter, especially in hybrid or electrical vehicles
- Secondary rectification
- LLC topologies
- Phase shift topologies

### Description

This high voltage Schottky rectifier is suitable for high frequency switch mode power supplies.

Packaged in ISOTOP, the STPS200170TV1Y is intended for use in secondary rectification applications and more precisely in DC/DC converters in hybrid and electrical vehicles.

Product status link	
<a href="#">STPS200170TV1Y</a>	
Product summary	
Symbol	Value
$I_{F(AV)}$	2 x 100 A
$V_{RRM}$	170 V
$T_j$ (max.)	175 °C
$V_F$ (typ.)	0.63 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values, per diode at  $T_{amb} = 25\text{ °C}$ , unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage ( $T_j = -40\text{ °C}$ to $+175\text{ °C}$ )		170	V
$I_{F(RMS)}$	Forward rms current		200	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$ , square wave	$T_C = 140\text{ °C}$ , per diode	100	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10\text{ ms}$ sinusoidal	700	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}$ , $T_j = 125\text{ °C}$	7200	W
$T_{stg}$	Storage temperature range		-55 to +175	$^{\circ}\text{C}$
$T_j$	Operating junction temperature range <sup>(1)</sup>		-40 to +175	$^{\circ}\text{C}$

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameters**

Symbol	Parameter	Max. value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	0.4
		Total	0.2

For more information, please refer to the following application note:

- AN5088: Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R$ <sup>(1)</sup>	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		200	$\mu\text{A}$
		$T_j = 125\text{ °C}$		-	30	100	mA
$V_F$ <sup>(2)</sup>	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 100\text{ A}$	-		0.85	V
		$T_j = 150\text{ °C}$		-	0.63	0.68	
		$T_j = 25\text{ °C}$	$I_F = 200\text{ A}$	-		1.01	
		$T_j = 150\text{ °C}$		-	0.78	0.86	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the maximum conduction losses, use the following equation:

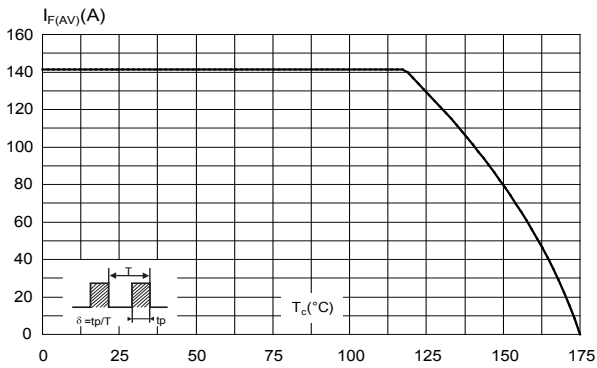
$$P = 0.5 \times I_{F(AV)} + 0.0018 \times I_F^2 \text{ (RMS)}$$

For more information, please refer to the following application notes related to the power losses:

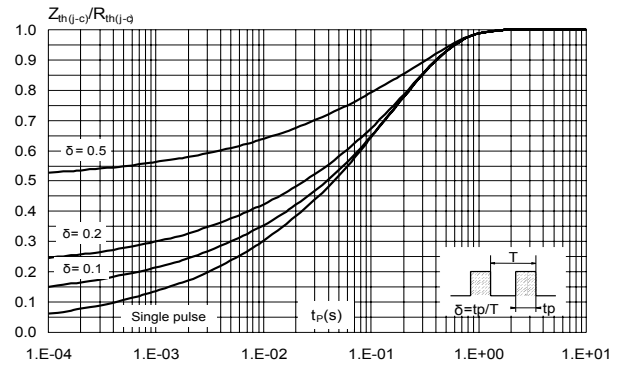
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses in a power diode

### 1.1 Characteristics (curves)

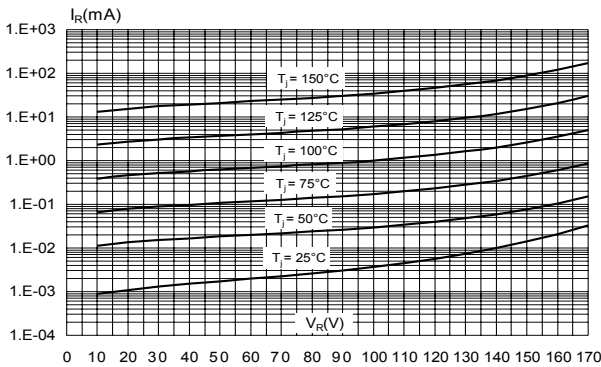
**Figure 1. Average forward current versus case temperature ( $\delta = 0.5$ , per diode)**



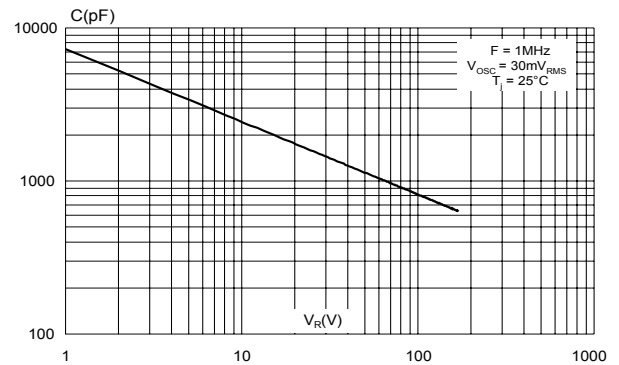
**Figure 2. Relative variation of thermal impedance junction to case versus pulse duration**



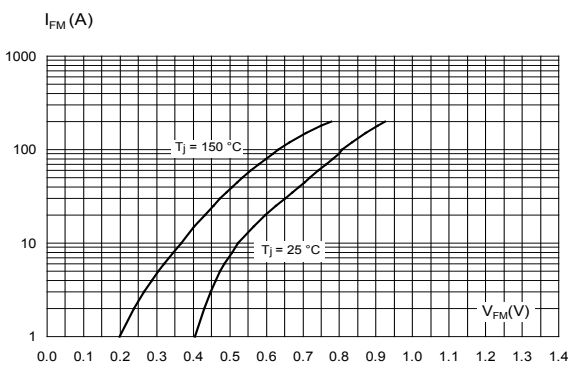
**Figure 3. Reverse leakage current versus reverse voltage applied (typical values per diode)**



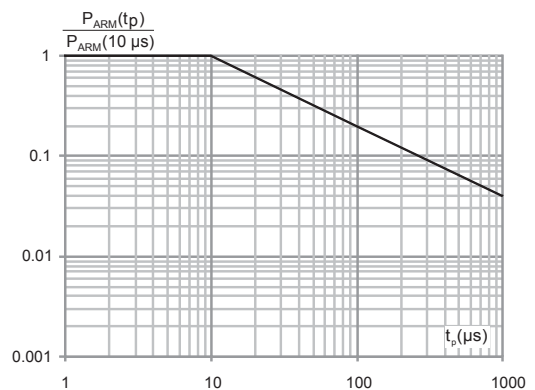
**Figure 4. Junction capacitances versus reverse voltage applied (typical values per diode)**



**Figure 5. Forward voltage drop versus forward current (typical values, per diode)**



**Figure 6. Normalized avalanche power derating versus pulse duration ( $T_j = 125^\circ\text{C}$ )**



## 2 Package information

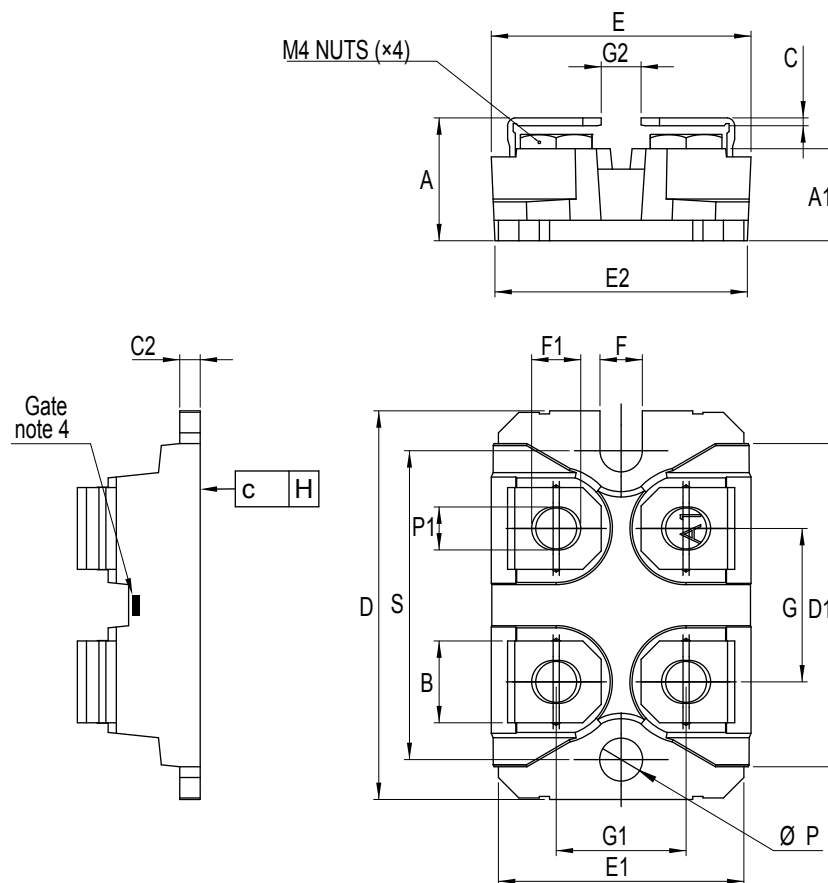
In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 ISOTOP package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 1.3 N·m
- Maximum torque value: 1.5 N·m

STMicroelectronics strongly recommend the use of the screws delivered with this product. The use of any other screws is entirely at the user's own risk and will invalidate the warranty.

Figure 7. ISOTOP package outline



**Table 4. ISOTOP package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches <sup>(1)</sup>	
	Min.	Max.	Min.	Max.
A	11.80	12.20	0.460	0.480
A1	8.90	9.10	0.350	0.358
B	7.80	8.20	0.307	0.323
C	0.75	0.85	0.030	0.033
C2	1.95	2.05	0.077	0.081
D	37.80	38.20	1.488	1.504
D1	31.50	31.70	1.240	1.248
E	25.15	25.50	0.990	1.004
E1	23.85	24.15	0.939	0.951
E2	24.80		0.976	
G	14.90	15.10	0.587	0.594
G1	12.60	12.80	0.496	0.504
G2	3.50	4.30	0.138	0.169
F	4.10	4.30	0.161	0.169
F1	4.60	5.00	0.181	0.197
H	-0.05	0.10	-0.002	0.004
Diam P	4.00	4.30	0.157	0.169
P1	4.00	4.40	0.157	0.173
S	30.10	30.30	1.185	1.193

1. Inches given for reference only

### 3 Mounting information

#### 3.1 Mounting on heatsink

Figure 8. Screws distance

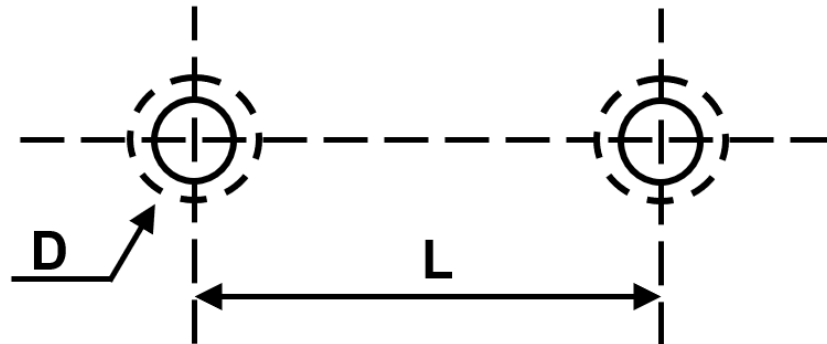


Table 5. Heatsink specification

Parameter	Value
Flatness (max concavity or convexity between fixing holes)	$\leq 20 \mu\text{m}$ (0.78 mils)
Surface finish	$\pm 1.2 \mu\text{m}$ ( $\pm 0.05$ mils)
Fixing holes	D = M4 L = 30 + 3 mm (1.181 + 0.012 inch)

Table 6. Mounting specification

Parameter	Value
Fixing screw	M4 + lock washer
Torque	$1.3 \pm 0.2 \text{ N}\cdot\text{m}$ ( $7.6 \pm 1.2 \text{ LBS}\cdot\text{inch}$ )
Fixing holes	$\leq 0.05 \text{ }^\circ\text{CW}$

Table 7. Connectors

Parameter	Value
Screws	See figure 9
Torque	$1.3 \pm 0.2 \text{ N}\cdot\text{m}$ ( $7.6 \pm 1.2 \text{ LBS}\cdot\text{inch}$ )
Pull test (fast on pins)	$\leq 80 \text{ N}$
Twist test	N/A
Contact area (screw version)	$45 \text{ mm}^2$
Lead inductance	$\leq 5 \text{ nH}$

Figure 9. Mounting section

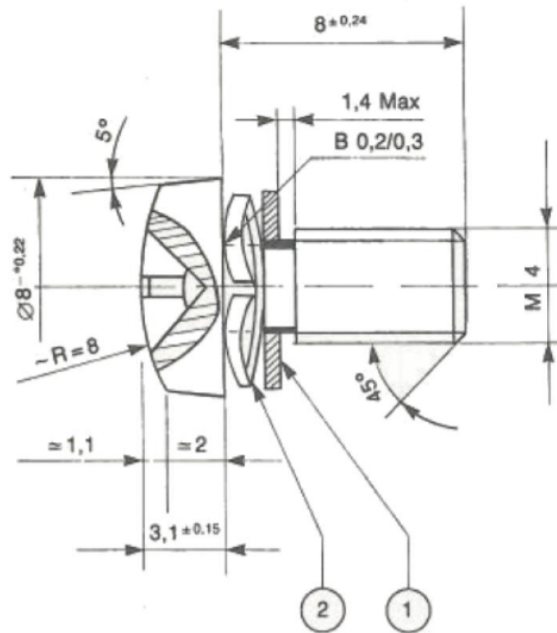
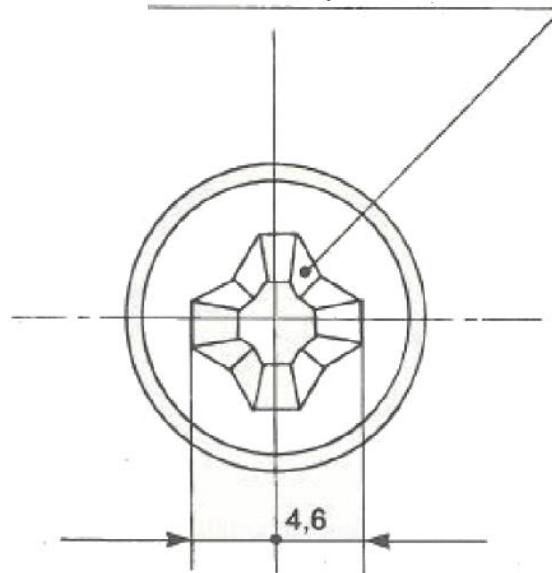


Figure 10. Cross form

Cruciform footprint



For more information, please refer to the following technical note related to the mounting :

- TN1331: Assembly recommendations for STMicroelectronics ISOTOP package

## 4 Ordering information

**Table 8. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS200170TV1Y	STPS 200170TV1Y	ISOTOP	27 g without screws	10 with screws	Tube



## Revision history

**Table 9. Document revision history**

Date	Version	Changes
02-Mar-2010	1	First issue.
07-Oct-2011	2	Added torque values in Section 2.
12-Nov-2015	3	Updated features in cover page. Text added in Section 2.
16-Apr-2018	4	Removed figures 3 and 10. Updated Section Features, Section Description and Table 1. Absolute ratings (limiting values, per diode at $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified).
23-Nov-2020	5	Updated Features, Table 1. Absolute ratings (limiting values, per diode at $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified) and Table 2. Thermal resistance parameters. Removed conduction losses curves. Added Section 3 Mounting information. Minor text change.

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